PK618 (v1.1) April 3, 2015

100% Material Declaration Data Sheet for 7 Series RF900 Package

Average Weight: 9.8041 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.297103**	**3.030%**
	Silicon	7440-21-3	100.00	Basis	0.297103	
Bump					**0.014081**	**0.144%**
	Tin	7440-31-5	63.00	Basis	0.008871	
	Lead	7439-92-1	37.00	Basis	0.005210	
Underfill					**0.045000**	**0.459%**
	Bisphenol F/ Epichlorohydrin	9003-36-5	20.00	Basis	0.009000	
	Phenolic Resin	Trade Secret	15.00	Basis	0.006750	
	Bisphenol A Type Liquid Epoxy Resin	25068-38-6	5.00	Basis	0.002250	
	Amine Type Accelerator	Trade Secret	5.00	Basis	0.002250	
	Silicon Dioxide	60676-86-0	51.50	Basis	0.023175	
	Carbon Black	1333-86-4	1.00	Basis	0.000450	
	Additives	Trade Secret	2.50	Additive	0.001125	
Solder Paste					**0.006300**	**0.064%**
	Tin	7440-31-5	63.00	Metal	0.003969	
	Lead	7439-92-1	37.00	Metal	0.002331	
Capacitor 1					**0.023400**	**0.239%**
	Barium	12047-27-7	88.86	Ceramic	0.020793	
	Manganese	1313-13-9	1.43	Ceramic	0.000334	
	Nickel	7440-02-0	4.29	Internal Electrode	0.001003	
	Copper	7440-50-8	0.70	Termination	0.000164	
	Boron	1303-86-2	0.01	Termination	0.000003	
	Nickel	7440-02-0	3.57	Plating	0.000836	
	Tin	7440-31-5	0.90	Plating	0.000211	
	Lead	7439-92-1	0.24	Plating	0.000057	

© Copyright 2015 Xilinx, Inc. XILINX, the Xilinx logo, Virtex, Spartan, ISE, and other designated brands included herein are trademarks of Xilinx in the United States and other countries. All other trademarks are the property of their respective owners

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Capacitor 2					**0.004100**	**0.042%**
	Barium	12047-27-7	88.86	Ceramic	0.003643	
	Manganese	1313-13-9	1.43	Ceramic	0.000059	
	Nickel	7440-02-0	4.29	Internal Electrode	0.000176	
	Copper	7440-50-8	0.70	Termination	0.000029	
	Glass Oxide	65997-17-3	0.01	Termination	0.000001	
	Nickel	7440-02-0	3.57	Plating	0.000146	
	Tin	7440-31-5	0.86	Plating	0.000035	
	Lead	7439-92-1	0.29	Plating	0.000012	
Capacitor 3					**0.002500**	**0.025%**
	Barium	12047-27-7	71.29	Ceramic	0.001782	
	Manganese	1313-13-9	10.43	Ceramic	0.000261	
	Nickel	7440-02-0	2.00	Internal Electrode	0.000050	
	Copper	7440-50-8	11.57	Termination	0.000289	
	Boron	1303-86-2	0.21	Termination	0.000005	
	Nickel	7440-02-0	1.80	Plating	0.000045	
	Gold	7440-57-5	2.70	Plating	0.000068	
Capacitor 4					**0.012880**	**0.131%**
	Barium	12047-27-7	72.40	Ceramic	0.009325	
	Manganese	1313-13-9	10.60	Ceramic	0.001365	
	Nickel	7440-02-0	4.00	Internal Electrode	0.000515	
	Copper	7440-50-8	5.80	Termination	0.000747	
	Glass Oxide	65997-17-3	0.20	Termination	0.000026	
	Nickel	7440-02-0	2.66	Plating	0.000343	
	Tin	7440-31-5	3.99	Plating	0.000514	
	Lead	7439-92-1	0.35	Plating	0.000045	
Heat Sink					**5.818000**	**59.343%**
	Copper	7440-50-8	99.80	Main Material	5.806364	
	Nickel	7440-02-0	0.10	Main Material	0.005818	
	Nickel Sulfate	7786-81-4	0.10	Main Material	0.005818	
Heat Sink Adhesive					**0.120000**	**1.224%**
	Aluminium Oxide Al203	1344-28-1	70.00	Main Material	0.084000	
	Dimethyl Siloxane, Dimethylvinyl-terminated	68083-19-2	30.00	Main Material	0.036000	

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Solder Ball					**0.856618**	**8.737%**
	Tin	7440-31-5	63.00	Main Material	0.539669	
	Lead	7439-92-1	37.00	Main Material	0.316949	
Substrate					**2.604098**	**26.561%**
	Copper	7440-50-8	40.10		1.044296	
	Tin	7440-31-5	0.82		0.021224	
	Lead	7439-92-1	0.17		0.004427	
	Silver	7440-22-4	0.02		0.000417	
	BT Core	N/A	43.50		1.132886	
	ABF	N/A	13.14		0.342231	
	Solder Mask	Trade Secret	2.25		0.058617	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
09/17/13	1.0	Initial Xilinx release.
04/03/15	1.1	Correct error in Solder Paste

Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers ("Contractors"). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.